

■ Features

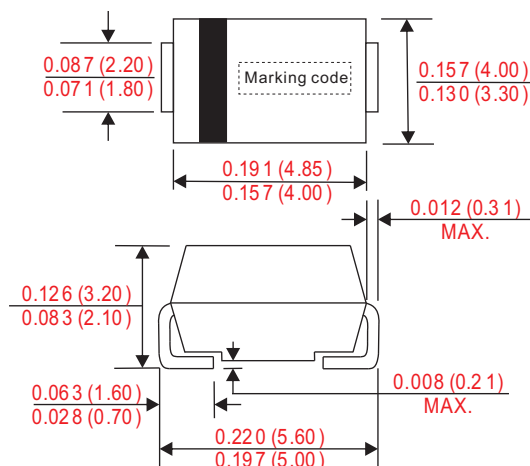
- Low profile surface mounted application in order to optimize board space.
- High current capability.
- Fast switching for high efficiency.
- High surge current capability.
- Glass passivated chip junction.
- Suffix "G" indicates Halogen free parts, ex. FS2AG
- Lead-free parts meet environmental standards of MIL-STD-19500 /228

■ Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, DO-214AA / SMB
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Weight : 0.003 ounce, 0.091 gram

■ Outline

SMB(DO-214AA)



Dimensions in inches and (millimeters)

■ Maximum ratings and electrical characteristics

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Conditions	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	$T_L = 90^\circ\text{C}$	I_O			2.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC method)	I_{FSM}			50	A
Reverse current	$V_R = V_{RRM} \quad T_A = 25^\circ\text{C}$	I_R			5.0	uA
	$V_R = V_{RRM} \quad T_A = 125^\circ\text{C}$				100	
Thermal resistance	Junction to ambient	$R_{\theta JA}$		20		°C/W
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		50		pF
Storage temperature		T_{STG}	-55		+150	°C

Symbol	Marking code	Max. repetitive peak reverse voltage V _{RRM} (V)	Max. RMS voltage V _{RMS} (V)	Max. DC blocking voltage V _R (V)	Max. forward voltage @2A, T _A = 25°C V _F (V)	Max. reverse recovery time(1) T _{rr} (ns)	Operating temperature T _J (°C)
FS2A	FS2A	50	35	50	1.30	150	-55 ~ +150
FS2B	FS2B	100	70	100			
FS2D	FS2D	200	140	200			
FS2G	FS2G	400	280	400		250	
FS2J	FS2J	600	420	600			
FS2K	FS2K	800	560	800		500	
FS2M	FS2M	1000	700	1000			

Note : 1. $I_F = 0.5A$, $I_R = 1.0A$, $I_{RR} = 0.25A$

■ Rating and characteristic curves

Fig. 1 - Forward Current Derating Curve

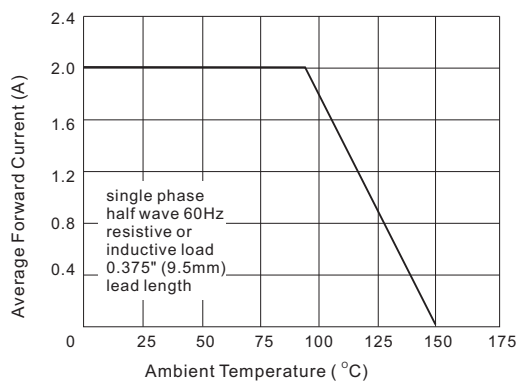


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current

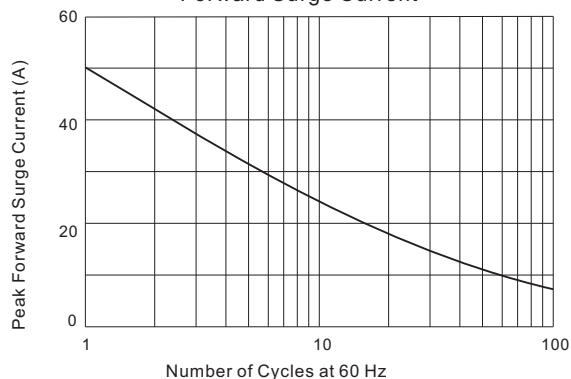


Fig. 3 - Typical Instantaneous Forward Characteristics

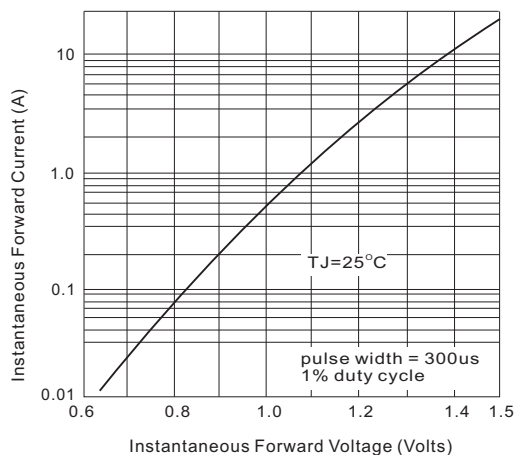


Fig. 4 - Typical Reverse Characteristics

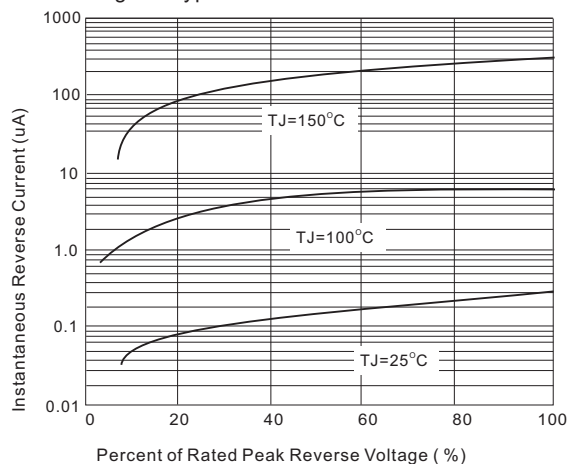
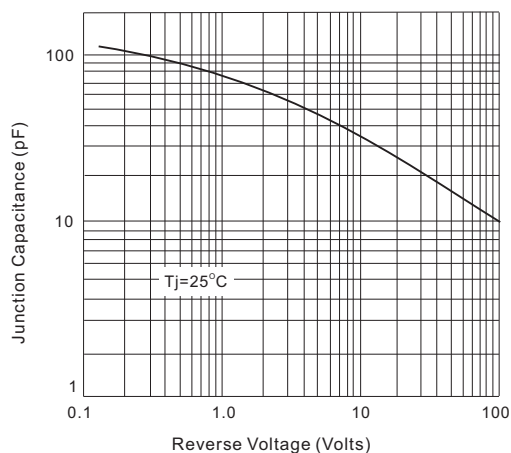
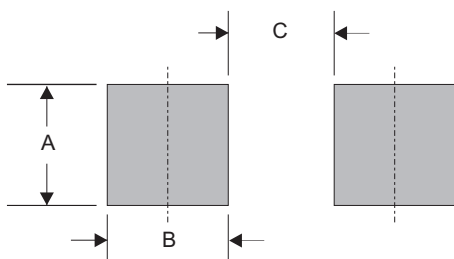


Fig. 5 - Typical Junction Capacitance



■ SMB foot print



A	B	C
0.091 (2.30)	0.098 (2.50)	0.071 (1.80)

Dimensions in inches and (millimeters)

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